

## **REMARKS**

In the Official Action dated December 15, 2004, the Examiner objected to Claims 5-6 under 37 C.F.R. 1.75, alleging that these claims are substantial duplicates of each other. The Examiner rejected Claims 1-7 under 35 U.S.C. §102(b), alleging that these claims are anticipated by Gabriel et al (U.S. Patent No. 6,472,231).

This response addresses each of the Examiner's objections and rejections. Accordingly, the present application is in condition for allowance. No new matter has been added. Entry of this amendment is respectfully requested and favorable consideration of all pending claims is therefore respectfully requested.

Applicants have cancelled claims 8-20 without prejudice as being drawn to a non-elected invention. Applicants reserve the right to file one or more divisional applications directed toward the deleted subject matter.

In response to the objection to claims 5-6, Applicants have changed the term "thinwire" to "fatwire" in claim 6. Support for this amendment can be found on page 2 of the specification which discloses the differences between "thinwire" and "fatwire." In view of this amendment, Applicants respectfully request reconsideration and withdrawal of this objection to claims 5 and 6.

With respect to the anticipation rejection, Applicants respectfully submit that Gabriel et al. do not teach each and every element of claim 1, as required under 35 U.S.C. §102.

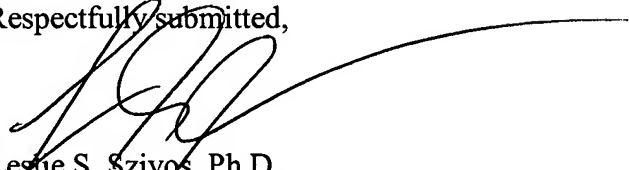
Gabriel et al. disclose an interconnect structure, but do not disclose a structure including a patterned organosilicate dielectric having sidewalls that are substantially non-altered by chemical or physical means. Moreover, Gabriel et al. teach

the use of conventional resist removal plasmas to enable resist removal during dual damascene (See column 8, lines 33-42 of Gabriel et al.) It is well documented by Kondoh et al., C.H. Ting, T.C. Chang et al., that conventional resist removal plasmas alter low-k dielectric sidewalls during CMOS dual damascene processing. Copies of Kondoh et al., C.H. Ting, and T.C. Chang et al., which are all published prior to the filing date of Gabriel et al., are enclosed herein for the Examiner's convenience. Furthermore, to the extent that Gabriel et al. would require one skilled in the art to use conventional resist removal plasmas, which would substantially alter the sidewalls of the claimed invention, Gabriel et al. teach away from the present invention.

Accordingly, the claimed invention is not anticipated by the disclosure of Gabriel et al. Applicants respectfully request reconsideration and withdrawal of this rejection of Claims 1-7 under 35 U.S.C. §102(b).

In view of the foregoing amendments and remarks, it is firmly believed that the present case is in condition for allowance, which action is earnestly solicited.

Respectfully submitted,



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Enclosures: (3) References